HAT2108R

Silicon N Channel Power MOS FET High Speed Power Switching

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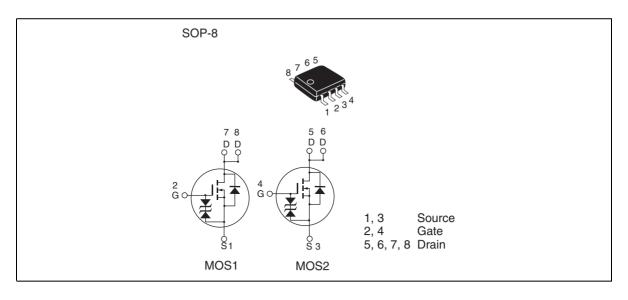
ADE-208-1574C (Z)

4th. Edition Aug. 2002

Features

- Low on-resistance
- Capable of 2.5 V gate drive
- Low drive current
- High density mounting

Outline





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Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DSS}	28	V	
Gate to source voltage	V _{GSS}	±12	V	
Drain current	I _D	11	A	
Drain peak current	Note1 D(pulse)	88	A	
Body-drain diode reverse drain current	I _{DR}	11	A	
Channel dissipation	Pch Note2	2	W	
Channel dissipation	Pch Note3	3	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	−55 to +150	°C	

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

^{2. 1} Drive operation : When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW \leq 10s

^{3. 2} Drive operation : When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW≤ 10s

Electrical Characteristics

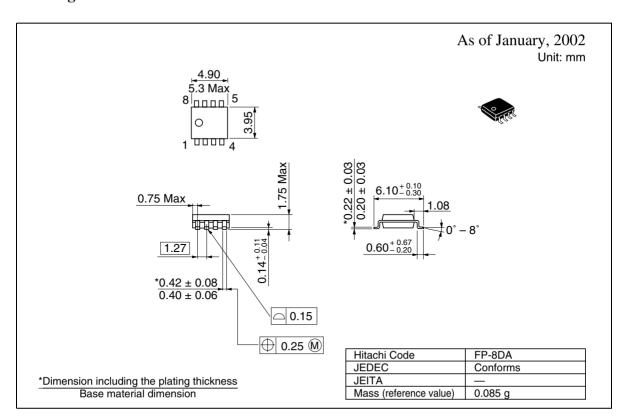
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{_{(BR)DSS}}$	28	_	_	V	$I_{D} = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	± 12	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 28 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{_{\mathrm{GS(off)}}}$	0.4	_	1.4	V	$V_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA}$
Static drain to source on state	R _{DS(on)}	_	12	15	mΩ	$I_{\rm D} = 5.5 \text{ A}, V_{\rm GS} = 4 \text{ V}^{\rm Note4}$
resistance	R _{DS(on)}	_	15	22	mΩ	$I_{D} = 5.5 \text{ A}, V_{GS} = 2.5 \text{ V}^{Note4}$
Forward transfer admittance	ly _{fs} l	17	28	_	S	$I_{D} = 5.5 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note4}}$
Input capacitance	Ciss	_	2200	_	pF	V _{DS} = 10 V
Output capacitance	Coss	_	400	_	pF	V _{GS} = 0
Reverse transfer capacitance	Crss	_	240	_	pF	f = 1 MHz
Total gate charge	Qg	_	16	_	nc	V _{DD} = 10 V
Gate to source charge	Qgs	_	5.2	_	nc	V _{GS} = 4 V
Gate to drain charge	Qgd	_	4.8	_	nc	I _D = 11 A
Turn-on delay time	t _{d(on)}	_	30	_	ns	$V_{GS} = 4 \text{ A}, I_{D} = 5.5 \text{ A}$
Rise time	t,	_	35	_	ns	$V_{DD} \cong 10 \text{ V}$
Turn-off delay time	t _{d(off)}	_	70	_	ns	$R_L = 1.81 \Omega$
Fall time	t _f	_	25	_	ns	$R_g = 4.7 \Omega$
Body-drain diode forward voltage	V _{DF}	_	0.85	1.11	V	IF = 11 A, V _{GS} = 0 Note4
Body-drain diode reverse recovery time	t _{rr}	_	40	_	ns	IF = 11 A, V _{GS} = 0 diF/ dt = 50 A/μs

Notes: 4. Pulse test

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Package Dimensions



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